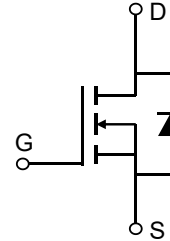


### Description

#### Features

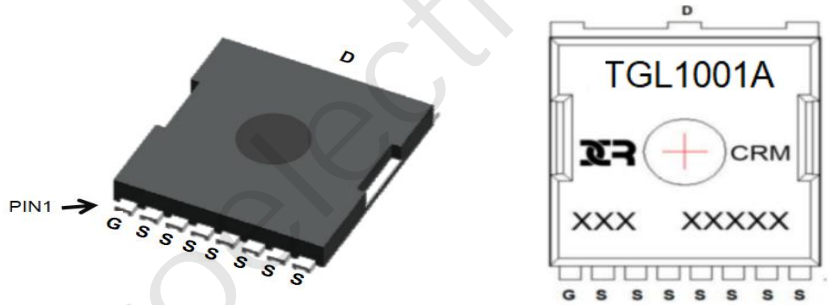
- 100V, 402A  
 $R_{DS(ON)}$  Typ = 1.2mΩ @  $V_{GS} = 10V$   
 $R_{DS(ON)}$  Typ = 1.45mΩ @  $V_{GS} = 4.5V$
- Advanced Split Gate Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- 100% UIS TESTED!
- 100%  $\Delta V_{ds}$  TESTED!



Schematic Diagram

#### Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

#### Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMTGL1001A	CRMTGL1001A	TOLL	TAPING	13"	2000	10000

#### Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	100	V
$V_{GS}$	Gate-to-Source Voltage	±20	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$	402
		$T_C = 100^\circ\text{C}$	241.2
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	1608	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	1056	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}$	463
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.27	°C/W
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	°C

### Electrical Characteristics ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
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#### Off Characteristics

$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}$ , $V_{GS} = 0\text{V}$	100	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 100\text{V}$ , $V_{GS} = 0\text{V}$	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{DS} = 0\text{V}$ , $V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA

#### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250\mu\text{A}$	1.2	1.7	2.2	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance <sup>(3)</sup>	$V_{GS} = 10\text{V}$ , $I_D = 30\text{A}$	-	1.2	1.56	mΩ
		$V_{GS} = 4.5\text{V}$ , $I_D = 20\text{A}$	-	1.45	1.9	mΩ

#### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{V}$ , $V_{DS} = 50\text{V}$ , $f = 100\text{KHz}$	-	11085	-	pF
$C_{oss}$	Output Capacitance		-	3523	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	85	-	pF
$Q_g$	Total Gate Charge	$V_{GS} = 0$ to $10\text{V}$ $V_{DS} = 50\text{V}$ , $I_D = 30\text{A}$	-	125	-	nC
$Q_{gs}$	Gate Source Charge		-	45	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge		-	20	-	nC

#### Switching Characteristics

$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 10\text{V}$ , $V_{DD} = 50\text{V}$ $I_D = 30\text{A}$ , $R_{GEN} = 6\Omega$	-	35	-	ns
$t_r$	Turn-On Rise Time		-	63	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	80	-	ns
$t_f$	Turn-Off Fall Time		-	77	-	ns

#### Drain-Source Diode Characteristics and Max Ratings

$I_S$	Maximum Continuous Drain to Source Diode Forward Current	$V_{GS} = 0\text{V}$ , $I_S = 30\text{A}$	-	-	402	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	1608	A
$V_{SD}$	Drain to Source Diode Forward Voltage		-	-	1.2	V
$t_{rr}$	Body Diode Reverse Recovery Time		-	100	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	135	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
  2.  $E_{AS}$  condition: Starting  $T_J = 25^\circ\text{C}$ ,  $V_{DD} = 50\text{V}$ ,  $V_G = 10\text{V}$ ,  $R_G = 25\text{ohm}$ ,  $L = 0.5\text{mH}$ ,  $I_{AS} = 65\text{A}$
  3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .

## Test Circuit

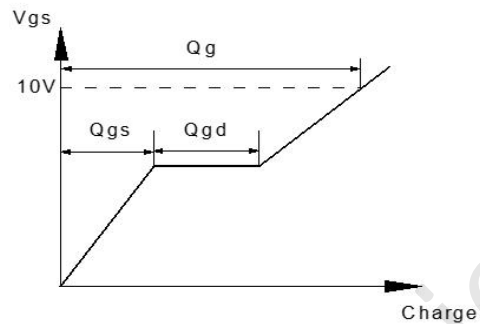
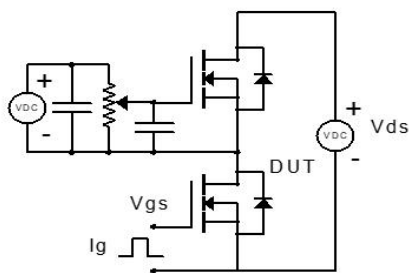


Figure 1: Gate Charge Test Circuit & Waveform

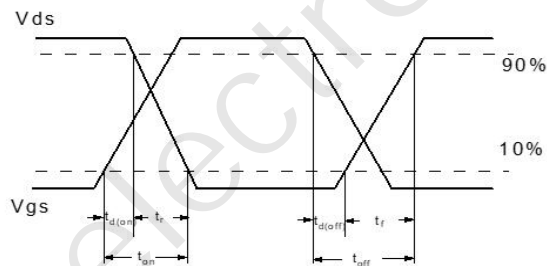
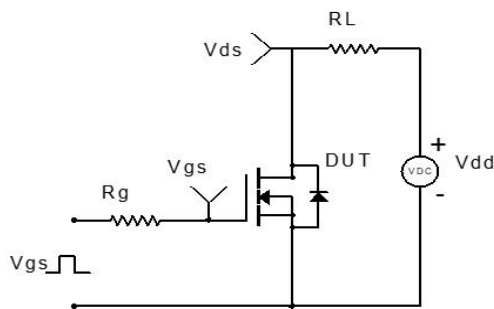


Figure 2: Resistive Switching Test Circuit & Waveform

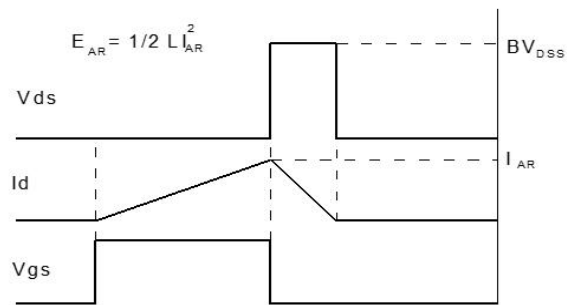
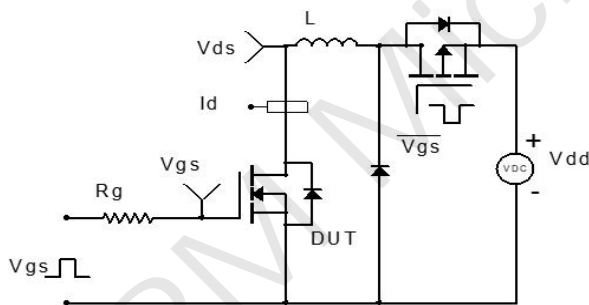


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

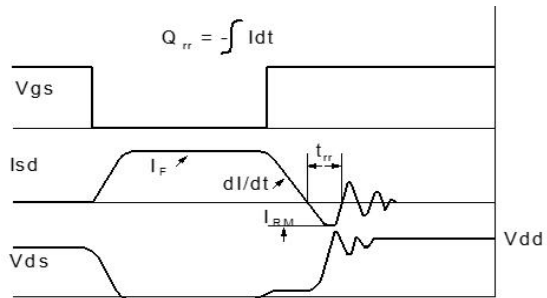
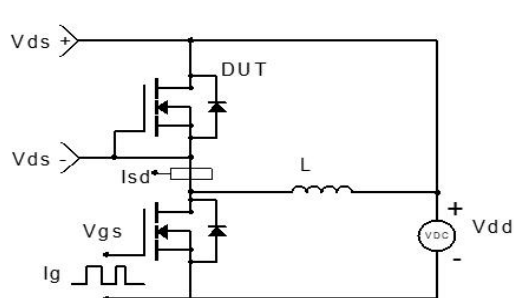
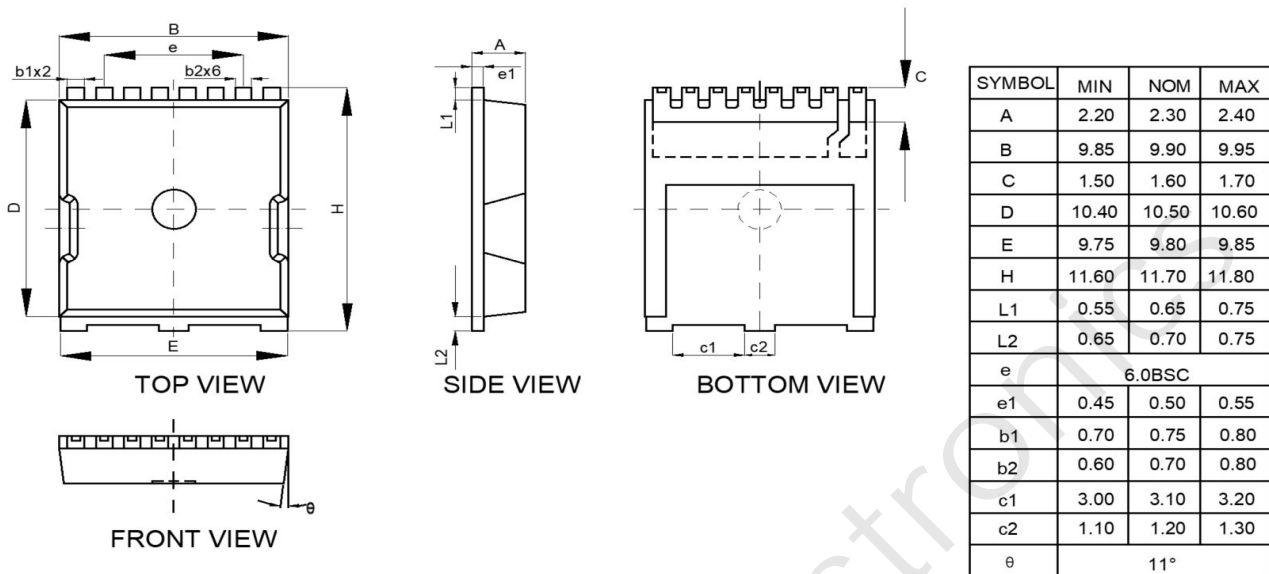


Figure 4: Diode Recovery Test Circuit & Waveform

### Package Mechanical Data(TOLL)




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